



First Call For Papers

2025 IEEE 16th International Conference on ASIC

Oct. 21-24, 2025, Crowne Plaza Hotel
Kunming, China

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2025 IEEE 16th International Conference on ASIC (ASICON 2025) will be held in Kunming, China, during Oct. 21-24, 2025. The conference is intended to provide an international forum for Integrated circuit designers, ASIC users, system integrators, IC manufacturers, process and device engineers, and CAD/CAE tool developers to present their latest progress, development and research results in their respective fields. The four-day event features keynote speeches, invited talks, regular paper presentations and tutorials, delivered by leading experts in the respective fields, on state-of-the-art Integrated circuits, design methodologies, devices, processes and manufacturing technologies. The Excellent Student Paper Award & Outstanding Young Scholar Paper Award will be announced at the conference. Additionally, an exhibition on EDA tools, foundry technologies, IC processing/testing facilities, and novel ASIC products will be held during the conference.

The Scope of the Conference

Papers are solicited in, but not limited to, the following:

I. Integrated Circuits and Design Techniques

- [1] **Analog IC**
 - Amplifiers,
 - Data converters (ADCs and DACs)
 - Power management ICs and Energy Harvesting
 - Clock generator
- [2] **Digital IC**
 - Low power technique
 - CPU, MCU, GPU, Embedded processors and DSP
 - Chaos/neural/fuzzy-logic circuits
 - Programmable devices (PLD, EPLD, HDPLD, FPGA, etc)
 - NOC
- [3] **Wireless, Wireline telecommunication and Optic Communication IC**
 - RF block circuits (LNA, Mixer, PA, Integrated Antenna and Switches),
 - RF Transceiver (Transmitter, receiver, PLL in RF transceiver), RFID
 - millimeter-wave circuits
 - Seders
 - THz circuits,
 - Laser Driver, TIA, CDR
- [4] **Memory**
 - DRAM & SRAM
 - Flash memory
 - Ferroelectric memory
 - Phase change memory, RRAM, MRAM
 - Novel memory
- [5] **Sensor, Image Processing and Bio-medical IC**
 - Sensor circuits
 - Graph theory and computing
 - Biomedical circuits and systems
 - Wearable systems
- [6] **FPGA and DSP**
 - FPGA architecture and circuits
 - Reconfigurable technique,
 - DSP architecture and circuits
 - FPGA and DSP application
- [7] **Special application IC**
 - Automobile IC,
 - Anti-Radiation IC
 - Ultra-High Voltage Circuits
- [8] **Design for Testing**
 - Digital/analog/mix-signal testing
 - Design for testability and reliability

